

| | Type | Hits | Search Text | DBs | Time Stamp |
|----|------|------|--|---|------------------|
| 1 | BRS | 26 | semiconductor adj chip and package and "heat slug" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 12:19 |
| 2 | BRS | 90 | chip and package and "heat slug" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 13:21 |
| 3 | BRS | 64 | chip and package and "heat slug" not (semiconductor adj chip and package and "heat slug") | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 14:13 |
| 4 | BRS | 201 | chip and package and slug not (chip and package and "heat slug") | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 16:04 |
| 5 | BRS | 9085 | chip and package and plate not (chip and package and slug not (chip and package and "heat slug")) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 16:04 |
| 6 | BRS | 205 | chip and package and cold adj plate not (chip and package and slug not (chip and package and "heat slug")) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 16:32 |
| 7 | BRS | 119 | 257/720.icls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 17:17 |
| 8 | BRS | 1 | (257/678.icls.) and "heat slug" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 17:19 |
| 9 | BRS | 5 | (257/678.icls.) and "slug" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 17:19 |
| 10 | BRS | 5 | (257/678.icls.) and slug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 17:22 |
| 11 | BRS | 3 | (257/678.icls.) and "cold plate" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 17:25 |
| 12 | BRS | 110 | (257/678.icls.) and plate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/23 17:25 |

| | Type | Hits | Search Text | DBs | Time Stamp |
|----|------|------|-----------------------------------|---|------------------|
| 13 | BRS | 3 | 5726079.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 13:10 |
| 14 | BRS | 1 | "5405809".PN. | USPAT | 2001/03/26 12:19 |
| 15 | BRS | 1 | "5471027".PN. | USPAT | 2001/03/26 12:22 |
| 16 | BRS | 1 | "5471027".PN. | USPAT | 2001/03/26 12:22 |
| 17 | BRS | 1 | "5359768".PN. | USPAT | 2001/03/26 12:22 |
| 18 | BRS | 1 | "5222014".PN. | USPAT | 2001/03/26 12:24 |
| 19 | BRS | 1 | "4959900".PN. | USPAT | 2001/03/26 12:24 |
| 20 | BRS | 1 | "4941255".PN. | USPAT | 2001/03/26 12:24 |
| 21 | BRS | 1 | "4794981".PN. | USPAT | 2001/03/26 12:25 |
| 22 | BRS | 1 | "4654966".PN. | USPAT | 2001/03/26 12:25 |
| 23 | BRS | 1 | "4571826".PN. | USPAT | 2001/03/26 12:25 |
| 24 | BRS | 1 | "3570115".PN. | USPAT | 2001/03/26 12:25 |
| 25 | BRS | 1 | "4023198".PN. | USPAT | 2001/03/26 12:25 |
| 26 | BRS | 1 | "4571826".PN. | USPAT | 2001/03/26 12:26 |
| 27 | BRS | 1 | "4654966".PN. | USPAT | 2001/03/26 12:26 |
| 28 | BRS | 1 | "5289346".PN. | USPAT | 2001/03/26 12:27 |
| 29 | BRS | 25 | (257/706.icls.) and heat adj slug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 13:16 |

| | Type | Hits | Search Text | DBs | Time Stamp |
|----|------|------|---|---|------------------|
| 30 | BRS | 0 | (257/70.icls.) and heat adj slug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 13:17 |
| 31 | BRS | 15 | (257/707.icls.) and heat adj slug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 13:18 |
| 32 | BRS | 6 | (257/778.icls.) and heat adj slug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 13:20 |
| 33 | BRS | 4 | (257/722.icls.) and heat adj slug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 13:26 |
| 34 | BRS | 1 | "5289346".PN. | USPAT | 2001/03/26 13:21 |
| 35 | BRS | 1 | "5359768".PN. | USPAT | 2001/03/26 13:21 |
| 36 | BRS | 1 | "5405809".PN. | USPAT | 2001/03/26 13:22 |
| 37 | BRS | 1 | "5410451".PN. | USPAT | 2001/03/26 13:22 |
| 38 | BRS | 6 | (438/122.icls.) and heat adj slug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 14:48 |
| 39 | BRS | 1 | (257/706.icls.) and heat adj slug and solder adj film | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 15:00 |
| 40 | BRS | 0 | (257.icls.) and heat adj slug and solder adj film | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 15:01 |
| 41 | BRS | 2 | heat adj slug and solder adj film | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 15:04 |
| 42 | BRS | 6 | slug and solder adj film | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:28 |

| | Type | Hits | Search Text | DBs | Time Stamp |
|----|------|------|---|---|------------------|
| 43 | BRS | 12 | slug and solder adj layer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:32 |
| 44 | BRS | 1462 | plate and solder adj layer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:33 |
| 45 | BRS | 225 | plate and solder adj layer and metal adj layer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:34 |
| 46 | BRS | 0 | heat adj plate and solder adj layer and metal adj layer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:34 |
| 47 | BRS | 103 | plate and solder adj layer and metal adj layer and chip | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:35 |
| 48 | BRS | 88 | plate and solder adj layer and metal adj layer and chip and substrate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:35 |
| 49 | BRS | 37 | plate and solder adj layer and metal adj layer and chip and substrate and bump | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 18:13 |
| 50 | BRS | 1 | cold adj plate and solder adj layer and metal adj layer and chip and substrate and bump | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 16:46 |
| 51 | BRS | 2 | 4926242.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/03/26 18:13 |

WEST**Freeform Search****Database:**

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Derwent World Patents Index
IBM Technical Disclosure Bulletins

Term:

5683937.pn. or 5811317.pn. or 5336364.pn. or
6060778.pn.

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|----------------|--|------------------|-----------------|
| USPT | 5683937.pn. or 5811317.pn. or 5336364.pn. or 6060778.pn. | 4 | <u>L16</u> |
| USPT | Heat adj sink and chip and substrate and adhesive adj layer and material and elastomer | 44 | <u>L15</u> |
| USPT | Heat adj sink and chip and substrate and adhesive adj layer and elastomer | 44 | <u>L14</u> |
| USPT | Heat adj sink and chip and substrate and adhesive adj layer and elastomer | 44 | <u>L13</u> |
| USPT | Heat adj sink and chip and substrate and anodizing adj layer | 2 | <u>L12</u> |
| USPT | (Heat adj sink and (cupper)) and chip and substrate | 3 | <u>L11</u> |
| USPT | (Heat adj sink and (cupper or "Al")) and chip and substrate | 3491 | <u>L10</u> |
| USPT | Heat adj sink and chip and substrate and underfilling adj material | 1 | <u>L9</u> |
| USPT | Heat adj sink and chip and substrate and underfilling adj material | 1 | <u>L8</u> |
| USPT | Heat adj sink and adhesion and material and "Ti/Pt/Au" | 14 | <u>L7</u> |
| USPT | Heat adj sink and adhesion and material | 1967 | <u>L6</u> |
| USPT | 6088915.pn. and heat adj sink and (silicon adj rubber or elastomer) | 1 | <u>L5</u> |
| USPT | 5359768.pn. and heat adj sink and (silicon adj rubber or elastomer) | 0 | <u>L4</u> |
| USPT | 5359768.pn. and heat adj sink and Al | 1 | <u>L3</u> |
| USPT | 5359768.pn. and heat adj sink and cupper | 0 | <u>L2</u> |
| USPT | 5359768.pn. and heat adj sink and cupper or Al | 2226085 | <u>L1</u> |